



## Product Change Notification - KSRA-12OKOU411

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**Date:**

07 Nov 2019

**Product Category:**

Ethernet Switches

**Affected CPNs:****Notification subject:**

CCB 3372 Final Notice: Qualification of ASE as a new assembly site for Micrel KSZ87XX device families available in 80L LQFP (10x10x1.4mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of ASE as a new assembly site for Micrel KSZ87XX device families available in 80L LQFP (10x10x1.4mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre Change:**

Assembled at TICIP using copper (Cu) bond wire and 1710A die attach material

**Post Change:**

Assembled at ASE using palladium coated copper with gold flash (CuPdAu) bond wire and CRM-1076WA die attach material

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp (TICP)	ASE Inc. Taiwan (ASE)
Wire material	Cu	CuPdAu
Die attach material	1710A	CRM-1076WA
Molding compound material	G631	G631
Lead frame material	C7025	C7025
Die Thickness	10 mils	14mils

**Impacts to Data Sheet:**

None

**Change Impact:**



None

**Reason for Change:**

To improve on-time delivery performance by qualifying ASE as a new assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

January 1, 2020 (date code: 2001)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	August 2018					-->	November 2019					-->	January 2020				
	31	32	33	34	35		44	45	46	47	48		1	2	3	4	5
Initial PCN Issue Date			X														
Qual Report Availability							X										
Final PCN Issue Date							X										
Estimated Implementation Date												X					

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**

**August 16, 2018:** Issued initial notification.

**November 1, 2018:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on January 1, 2019.

**November 7, 2019:** Re-issued final notification. Updated the estimated first ship date which is on January 1, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KSRA-12OKOU411\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8765CLXCC

KSZ8765CLXIC

KSZ8775CLXCC

KSZ8775CLXIC

KSZ8795CLXCC

KSZ8795CLXIC